



SLOVENSKI STANDARD SIST EN 61188-1-1:2001

01-marec-2001

Printed boards and printed board assemblies - Design and use - Part 1-1: Generic requirements - Flatness considerations for electronic assemblies

Printed boards and printed board assemblies - Design and use -- Part 1-1: Generic requirements - Flatness considerations for electronic assemblies

Leiterplatten und Flachbaugruppen - Konstruktion und Anwendung -- Teil 1: Allgemeine Anforderungen - Hauptabschnitt 1: Gesichtspunkte zur Ebenheit von elektronischen Baugruppen

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Cartes imprimées et cartes imprimées équipées - Conception et utilisation -- Partie 1-1: Prescriptions génériques - Considérations concernant la planéité d'ensembles électroniques

Ta slovenski standard je istoveten z: EN 61188-1-1:1997

ICS:

31.180 Vě \ ə ə \ ^: lə \ ɔ \ ɔ \ ^ \ ə \ ^ Printed circuits and boards
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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 61188-1-1

October 1997

ICS 31.180

Descriptors: Printed circuits, printed boards and assemblies, design, use, basic requirements, deviations from flatness, placement of SMD

English version

**Printed boards and printed board assemblies - Design and use
Part 1-1: Generic requirements - Flatness considerations
for electronic assemblies
(IEC 61188-1-1:1997)**

Cartes imprimées et cartes imprimées
équipées - Conception et utilisation
Partie 1-1: Prescriptions génériques
Considérations concernant la planéité
d'ensembles électroniques
(CEI 61188-1-1:1997)

Leiterplatten und Flachbaugruppen
Konstruktion und Anwendung
Teil 1-1: Allgemeine Anforderungen
Gesichtspunkte zur Ebenheit von
elektronischen Baugruppen
(IEC 61188-1-1:1997)

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This European Standard was approved by CENELEC on 1997-10-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 52/721/FDIS, future edition 1 of IEC 61188-1-1, prepared by IEC TC 52, Printed circuits, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61188-1-1 on 1997-10-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 1998-07-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 1998-07-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61188-1-1:1997 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61189-2	1997	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 2: Test methods for materials for interconnection structures	EN 61189-2 + corr. August	1997 1997

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**NORME
INTERNATIONALE**

**CEI
IEC**

**INTERNATIONAL
STANDARD**

61188-1-1

Première édition
First edition
1997-08

**Cartes imprimées et cartes imprimées équipées –
Conception et utilisation –**

**Partie 1-1:
Prescriptions génériques –
Considérations concernant la planéité
d'ensembles électroniques**

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**Printed boards and printed board assemblies –
Design and use –**

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**Part 1-1:
Generic requirements –
Flatness considerations for electronic assemblies**

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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –
DESIGN AND USE –

Part 1-1: Generic requirements –

Flatness considerations for electronic assemblies

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 61188-1-1 has been prepared by IEC technical committee 52: Printed circuits.

The text of this standard is based on the following documents:

FDIS	Report on voting
52/721/FDIS	52/738/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.